



Silicon photonics opportunities and challenges for high speed transmission

March Chen

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Industrial Technology Research Institute (ITRI)**

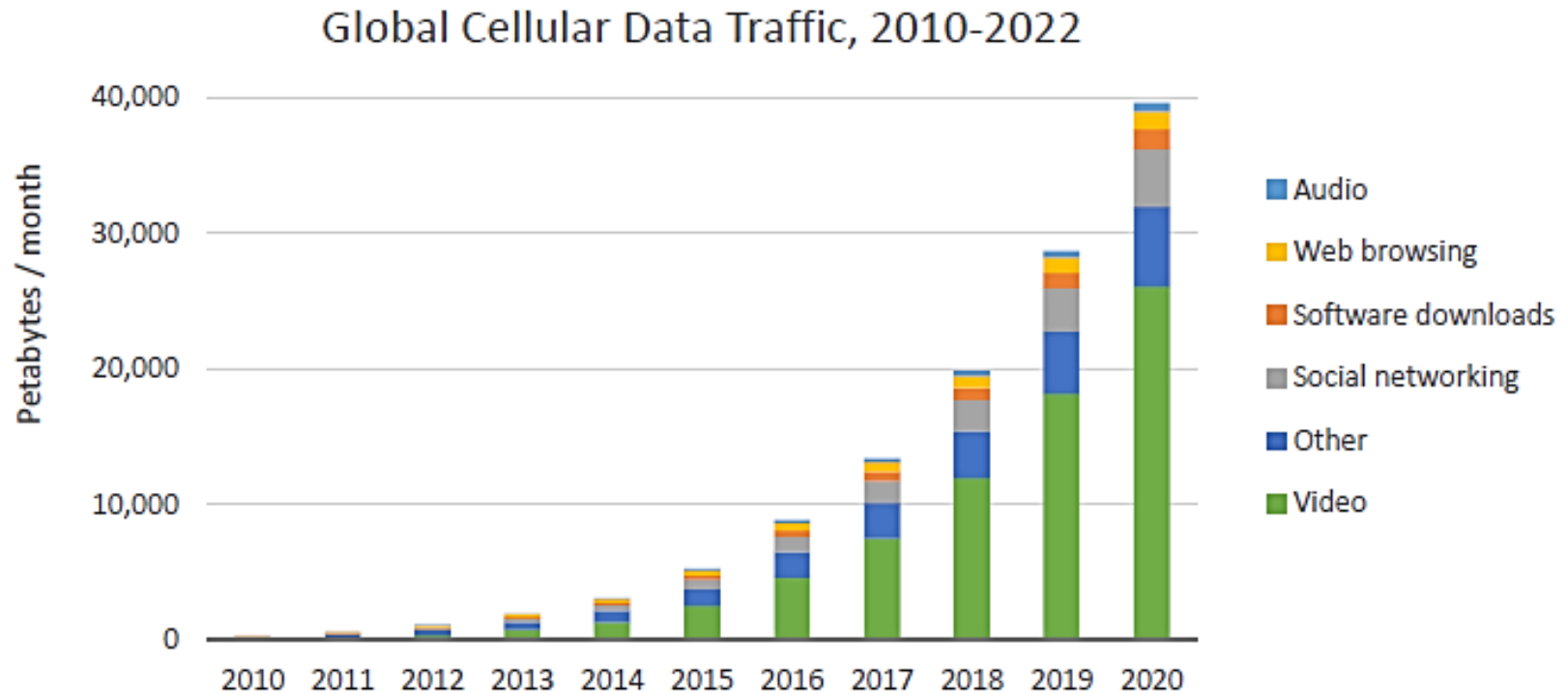
June 3rd 2019



- Market trend and request
- Why silicon photonics
- Challenges
- ITRI silicon photonics platform
- Conclusion



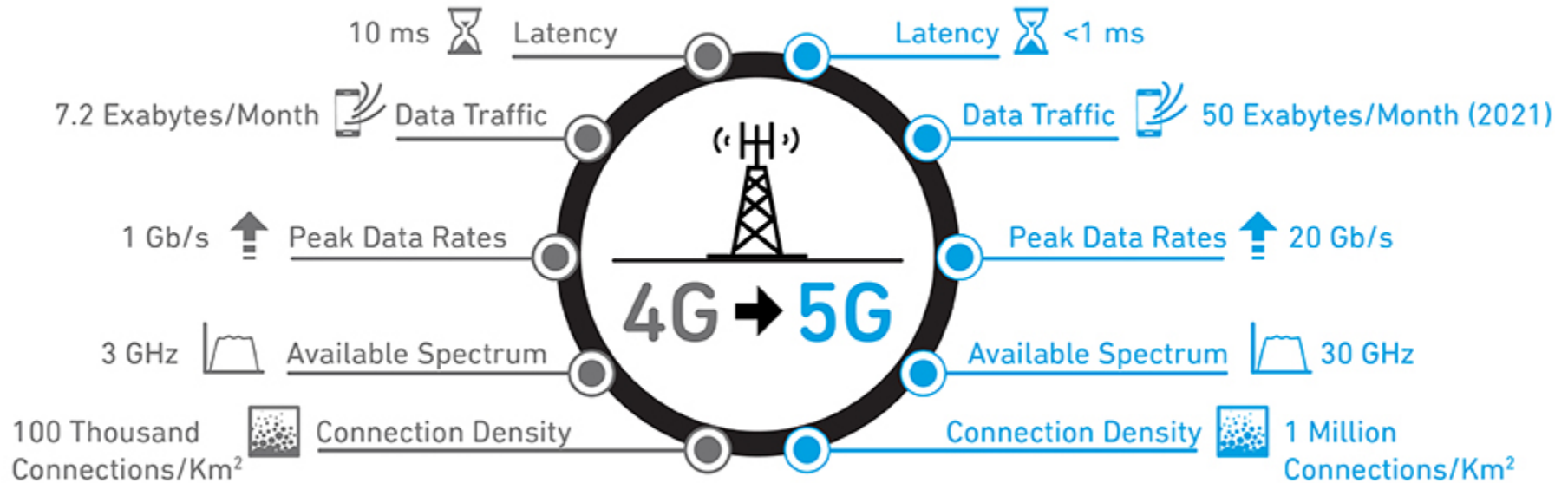
- 10 or 20 years ago, could you imagine the life today?
- Could you imagine what the world will be after 20 years?



- Video transmission occupies most of internet pipe
 - Grows up and up and up and...
- What action should we take for this mainstream?

Specs Upgrade in 5G

Comparing 4G and 5G



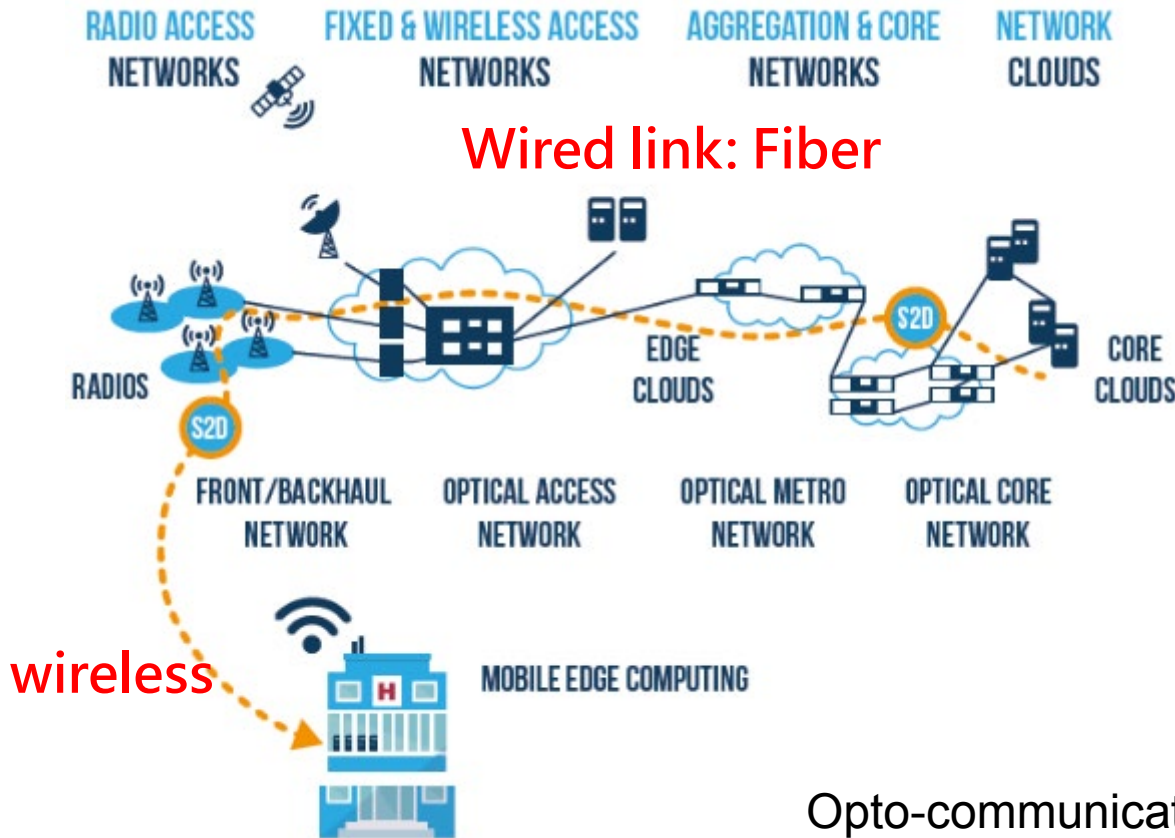
QORVO

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- 10X to 4G
- 5G tries to solve wireless issue, then?



5G + Fiber Network



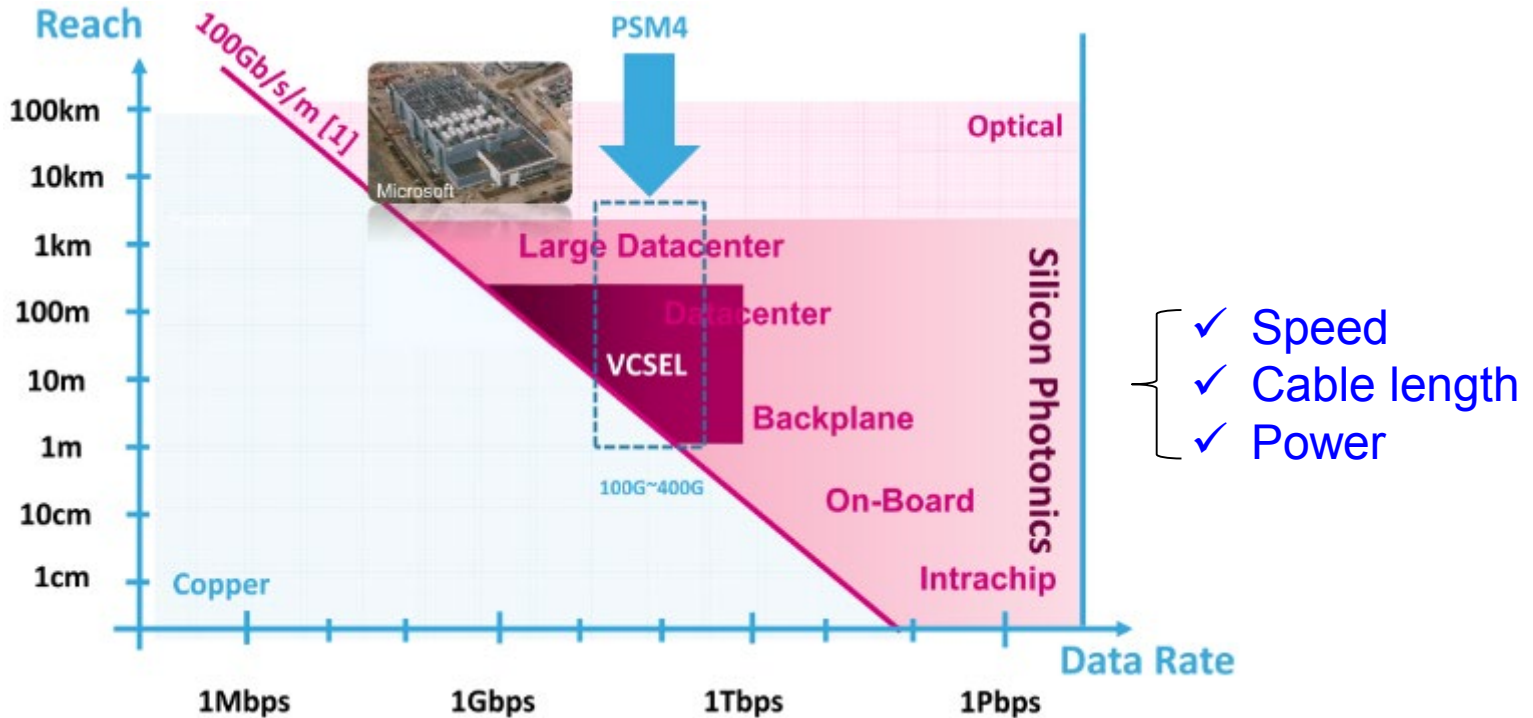
Deployment request:

- ✓ High coverage
- ✓ High speed
- ✓ Low latency
- ✓ Low cost

Opto-communication plays important role at:

- Base station
- Edge server
- Metro/core
- Data center

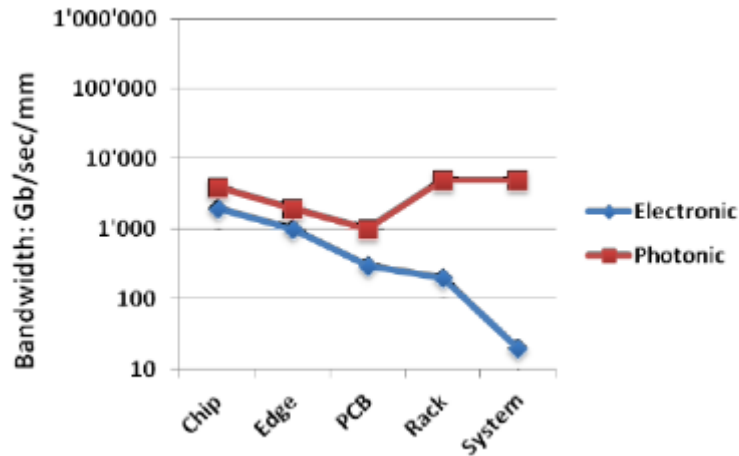
● Speed-length



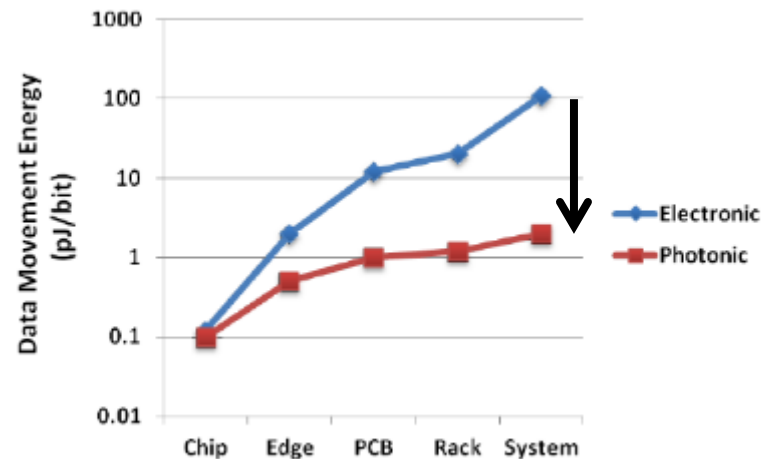
- ✓ Electrical/optical link boundary 100Gbps·m
- ✓ Electrical link: only single λ
- ✓ Optical link:
 - Multi- λ (CWDM, LAN-WDM, DWDM) per channel
 - Speed theoretically limited by electronics

● Power consumption

For exascale computing system



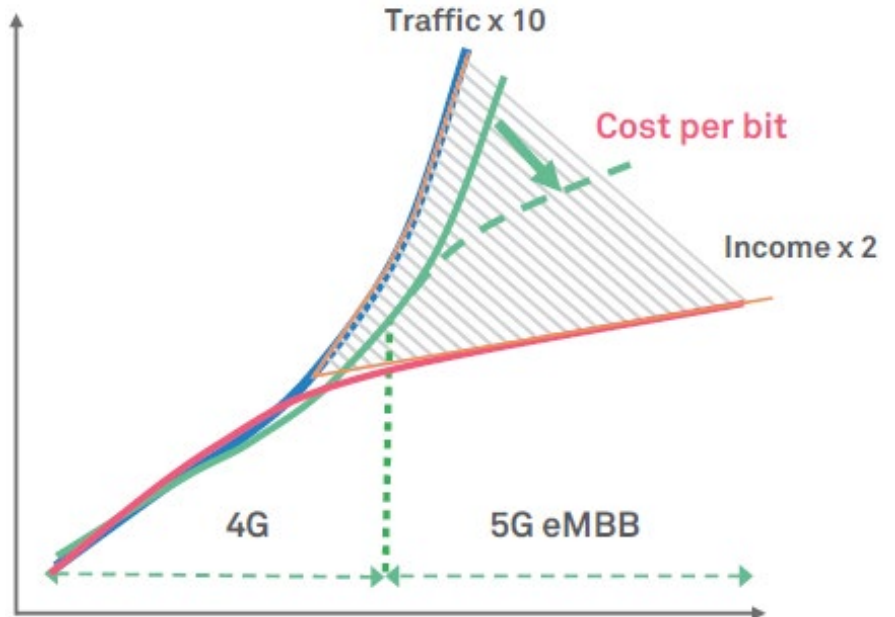
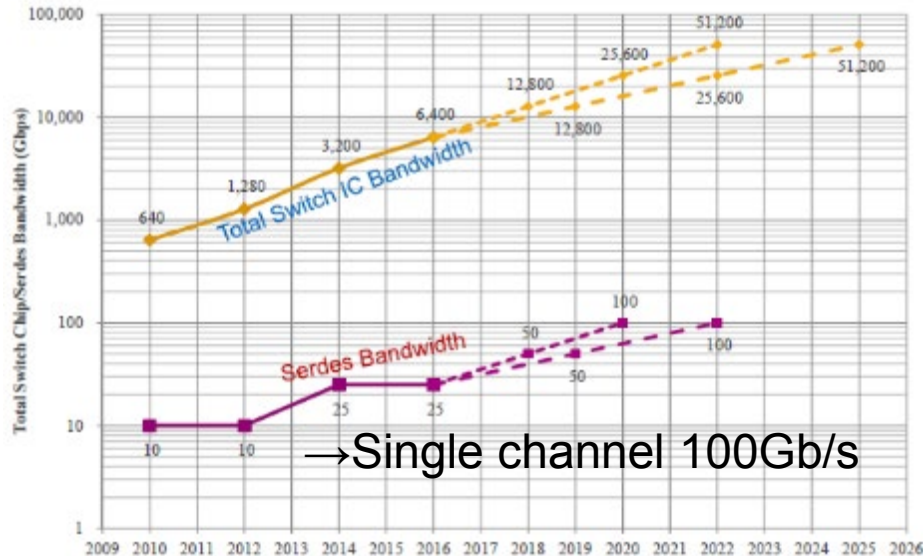
Bandwidth vs. system distance



Energy vs. system distance

- ✓ Photonic interconnect shows superior performance in bandwidth and energy consumption compared to electrical one
- ✓ Photonic interconnects applied in a rack computing system reduce around 2-order power consumption

Switch bandwidth → 51.2T+

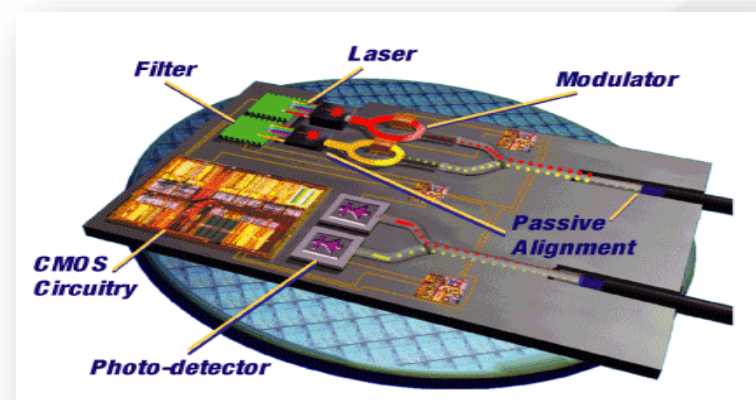
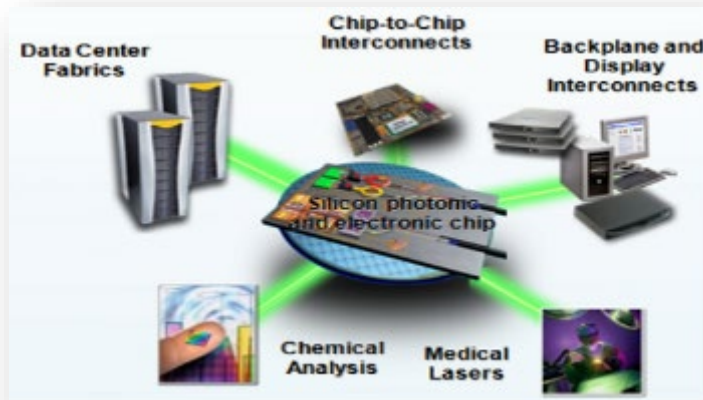
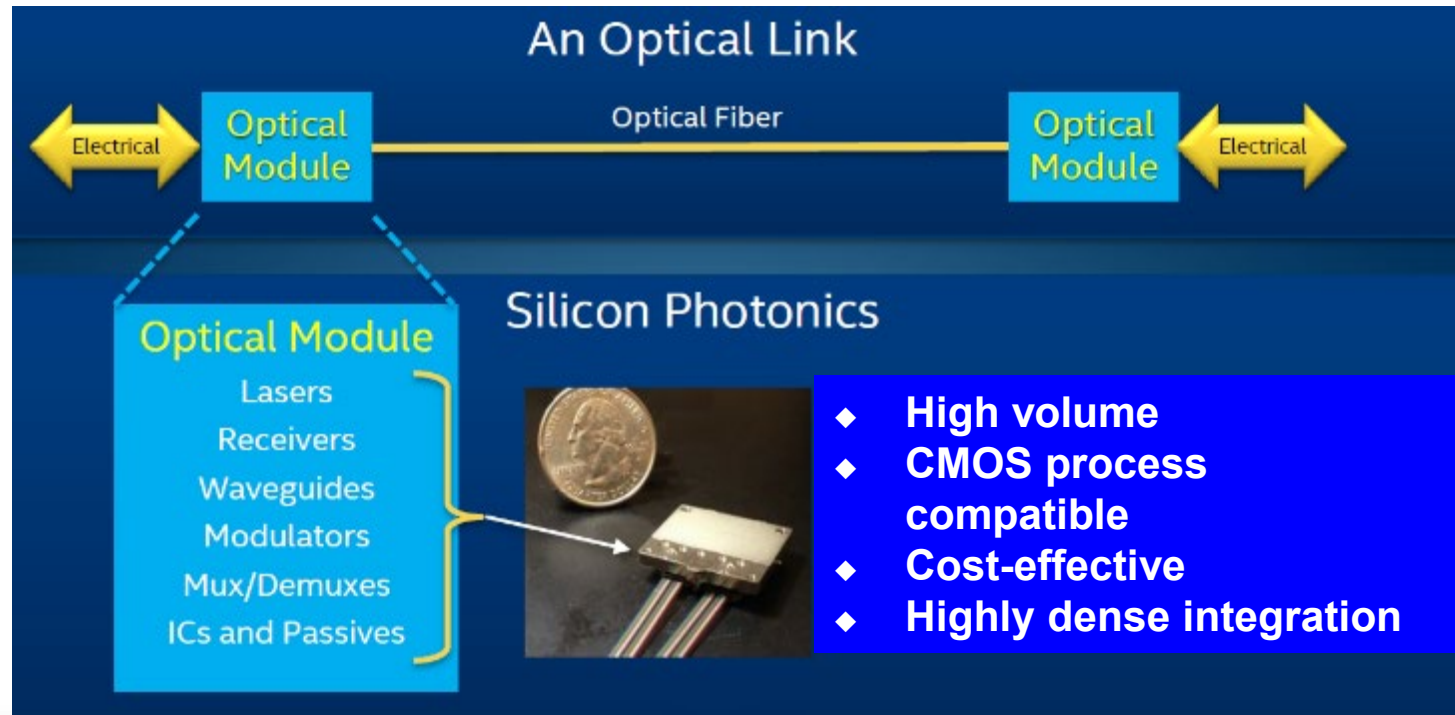


- Technical requirement :
 - single channel data rate 100Gb/s
 - switch bandwidth 51.2Tb/s
- Photonic replaces electronics
- Interface is bottleneck

- Technical development vs cost

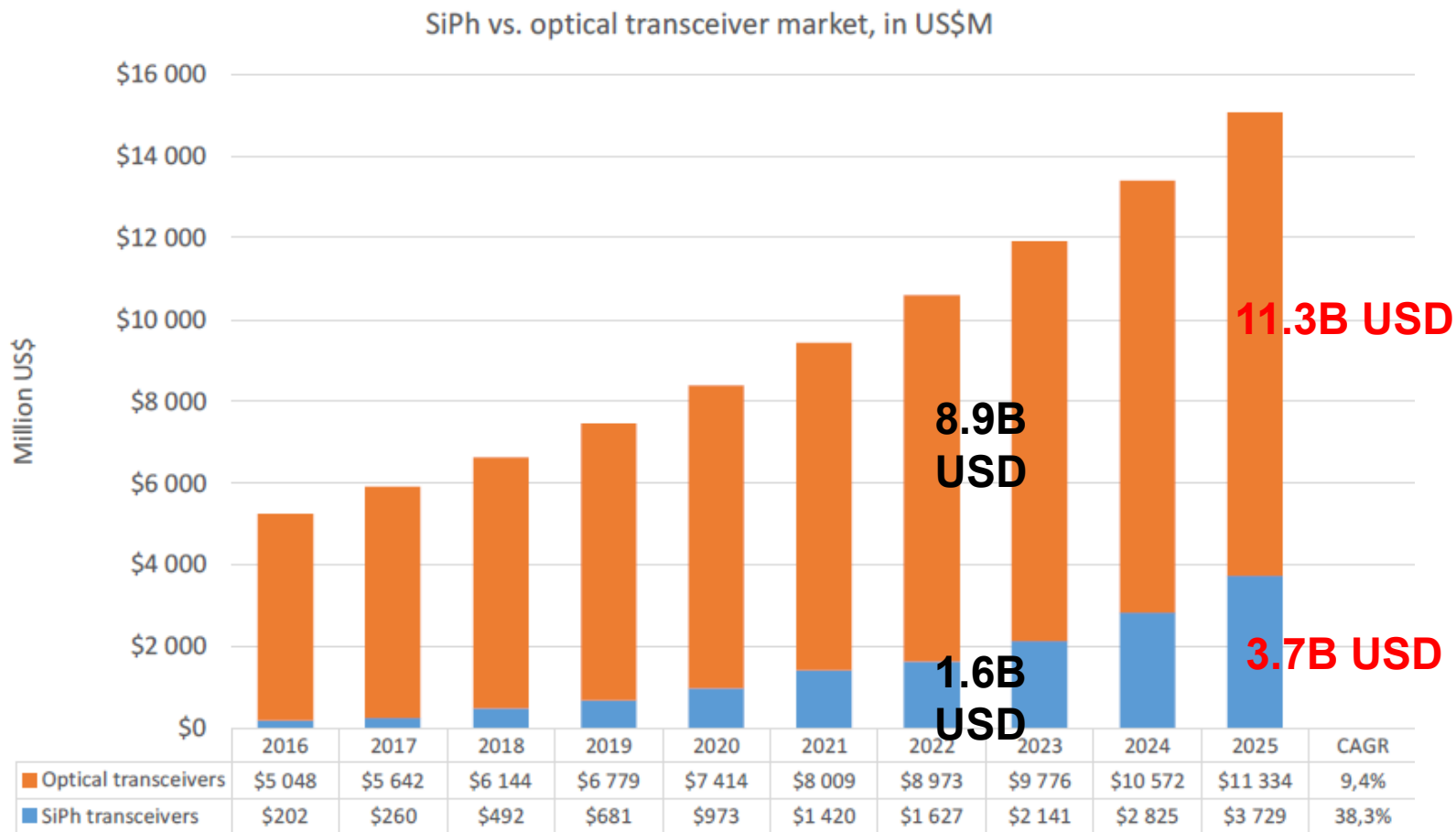
Silicon Photonics

What is Silicon Photonics?





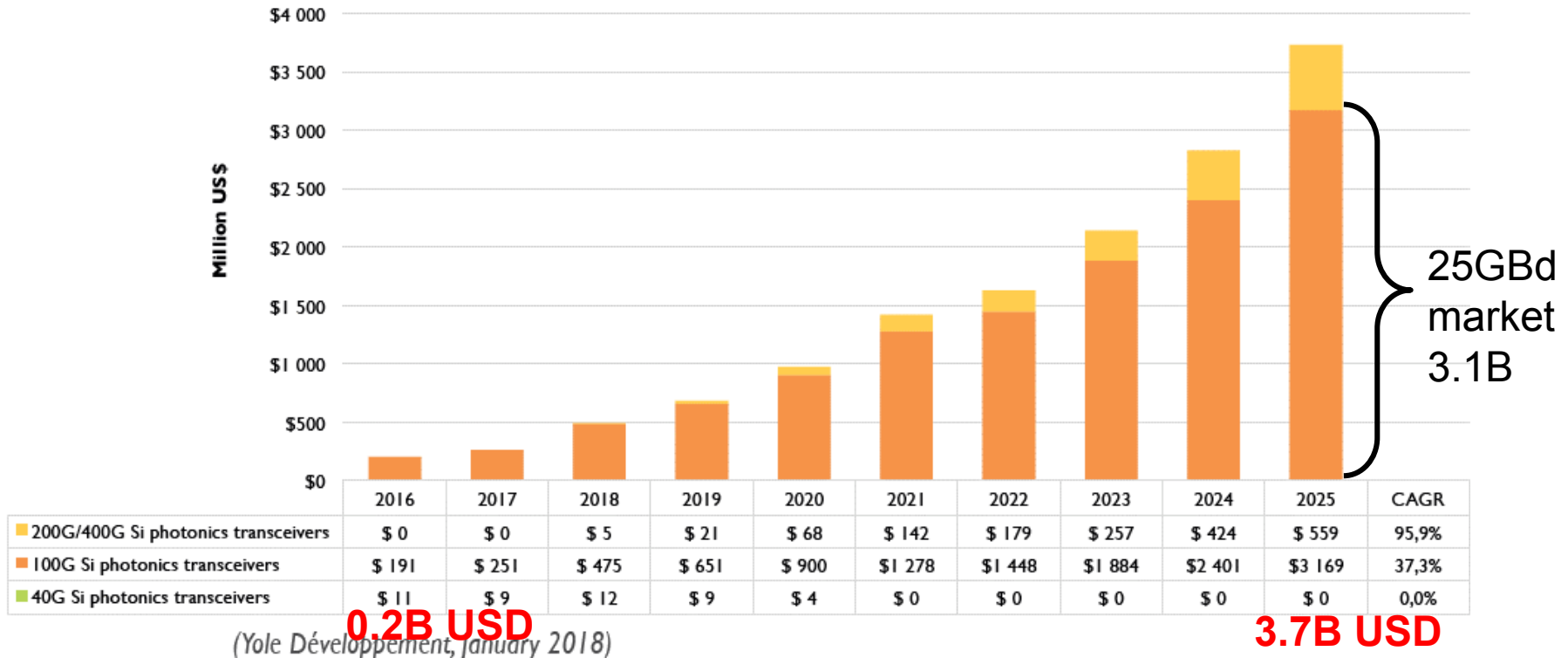
Optical Transceiver Market Grows



- With data center and 5G application raising, optical transceiver market will grow to 10.5B USD in 2021, 15B USD in 2025



Silicon photonics transceivers market forecast



- 100G dominate the SiPh transceiver market · even >80% in 2025
- 200G/400G market grows slowly in 2019
- 400G product comes this year but market is still a few years away

DATA CENTERS - ARCHITECTURE AND DATA RATE

SiPh will first be used for inter-DC. As data rate grows to 100G (outside VCSEL capabilities), SiPh will then move to inter-rack.

For distance > 500m
with data rate > 100G
(not accessible to
VCSEL), Si photonics
makes sense

**LONG SPAN/INTER BUILDINGS: 40G - 100G & beyond
(200G, 400G)**
Single-mode fiber
PSM4 or WDM4
500m - 10km

DR, FR, LR

Optical transceivers (transmitter-receiver) with detachable connectors



INTER RACK: 40G, moving to 100G
Multimode fiber
< 100m: active optical cable (AOC) with VCSELs
100 - 200m: SR4
Lowest-priced optical link

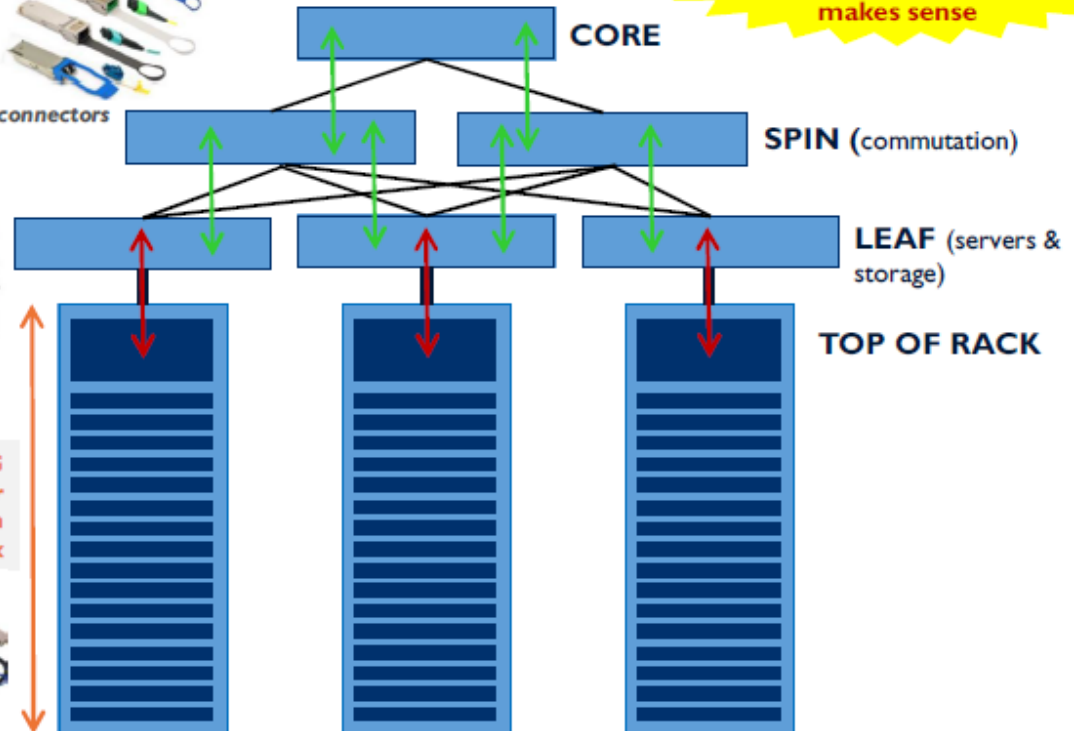
SR

AOC: transceivers with integrated fibers

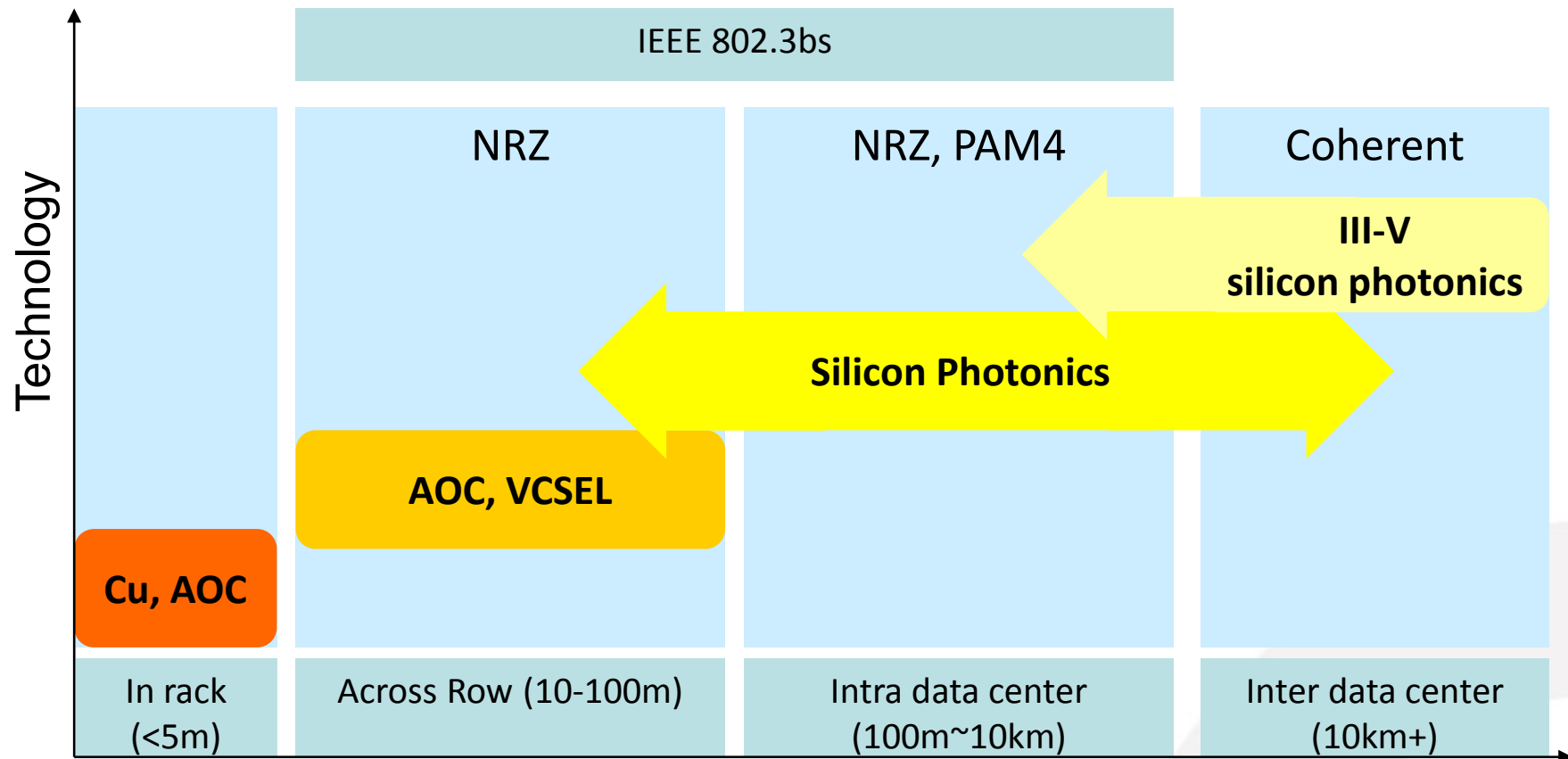


INTRA RACK: 10G, moving to 25G
Direct attach cable (DAC) in copper
3 - 5m
Lowest-priced link

DAC: copper cables



- Cable, VCSEL, Silicon photonics, III-V component, they have their own role in data center transceiving market



- AOC, VCSEL, silicon photonics, long-haul optics own the role themselves in data center transceiver market
- Silicon photonics is potentially suitable for all transmission links

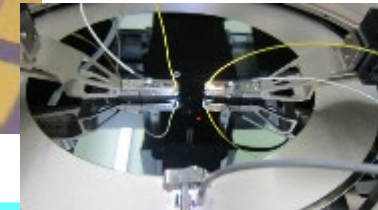
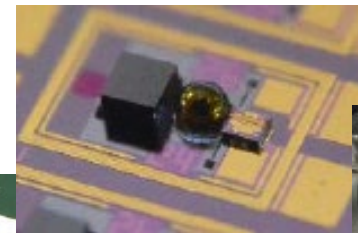
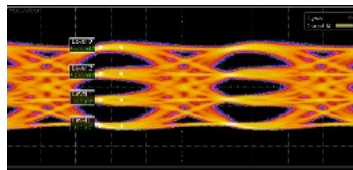
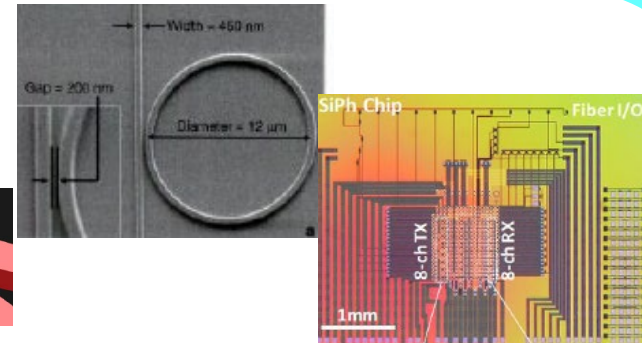
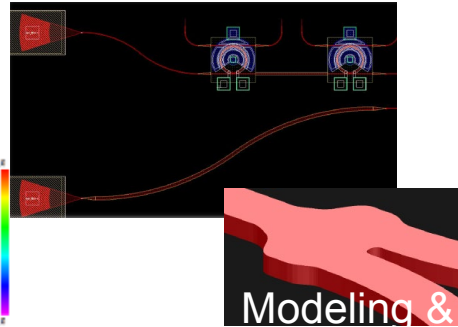
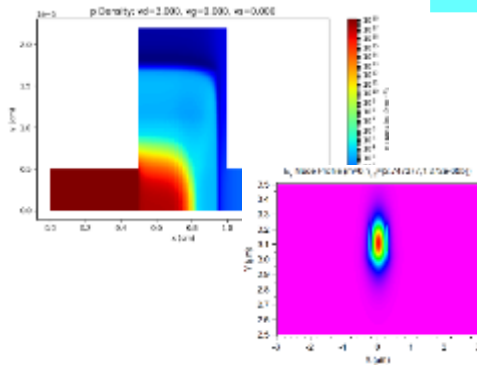


Silicon Photonics Challenges

1. software/design

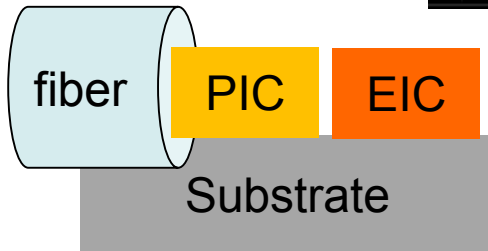
2. EDA

3. IC fabrication



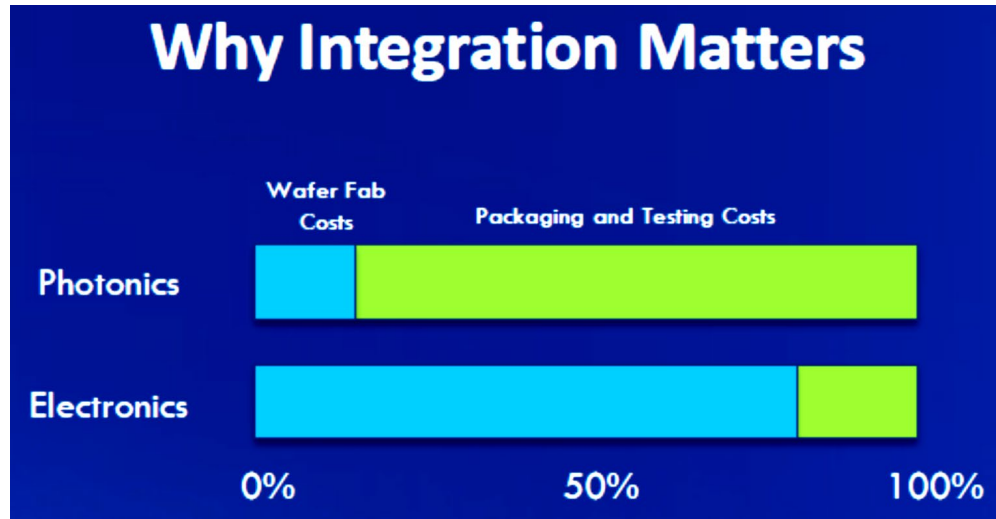
5. Optical/electrical package & testing

4. EO wafer/ level testing



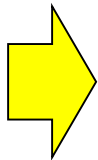
How to fit photonic events into silicon production chain?

Packaging & Testing Matters



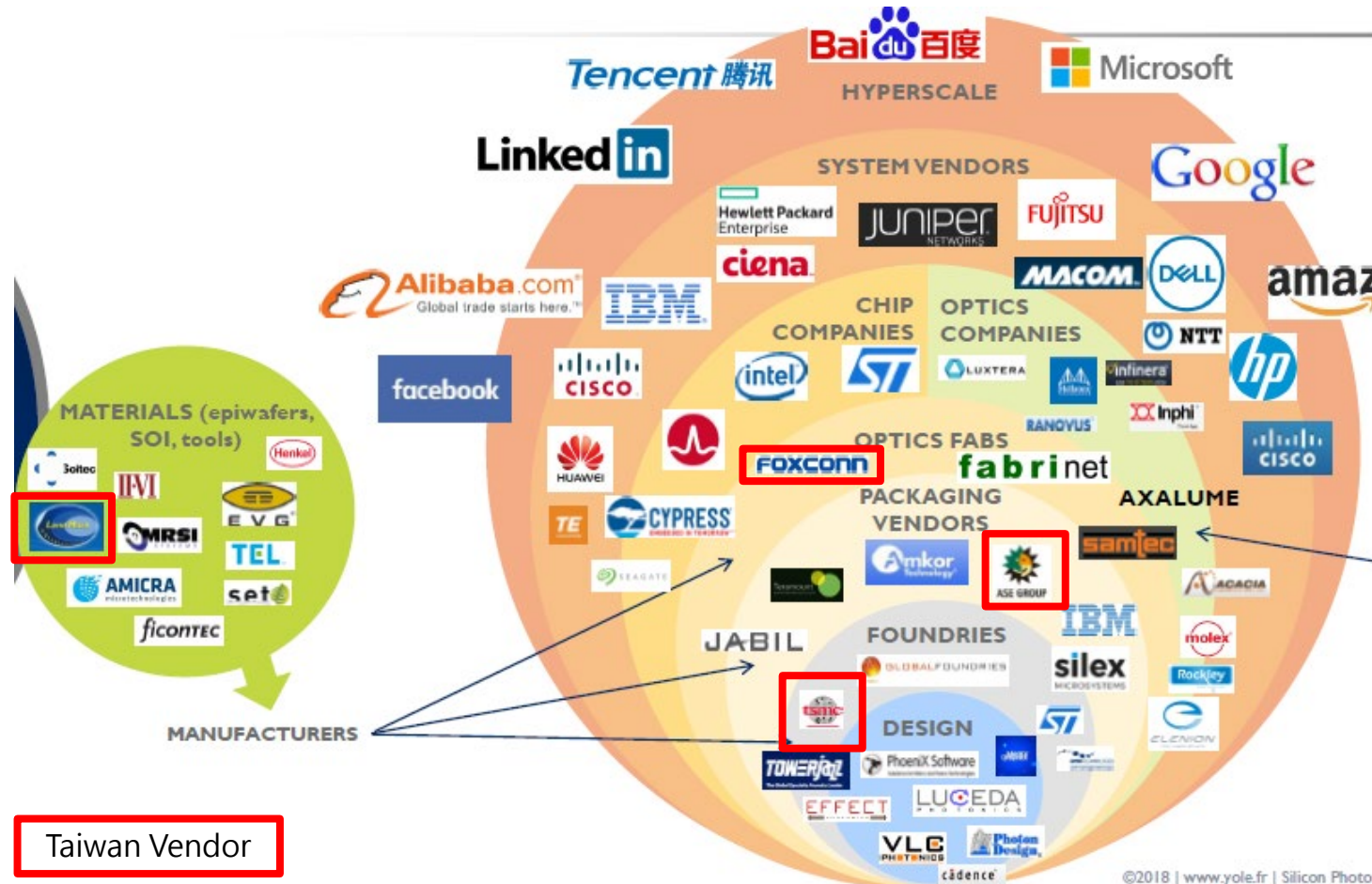
 Wafer fab costs
 Packaging and testing cost

- In electronic IC process, 80% of cost is wafer processes
- On photonic IC process, packaging and assembly are more than 80% !



Wafer fab realizes optical components on silicon semiconductor process, but packaging and testing are the key for commercialization

Worldwide Supply Chain



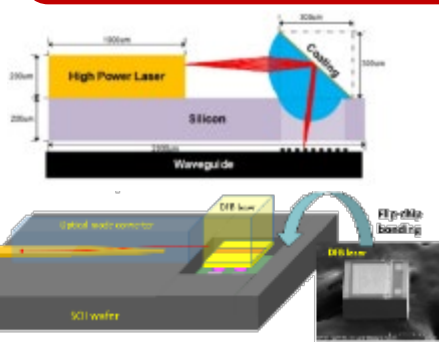
- Worldwide supply chain for production is now integrated by several leading companies
- To build up silicon photonics R&D platform to accelerate Taiwan's silicon photonics supply chain forming

Source: Yole 2018

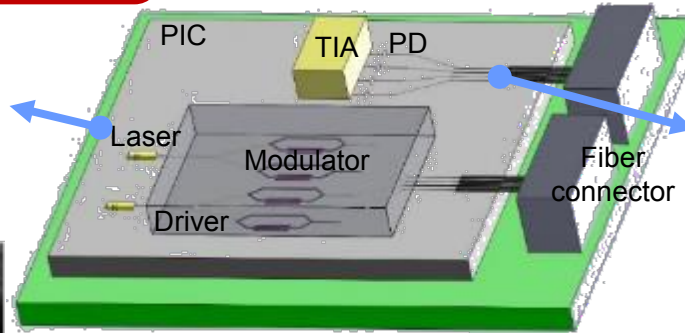


ITRI Silicon Photonics Technical Platform

B PIC packaging platform (Laser)

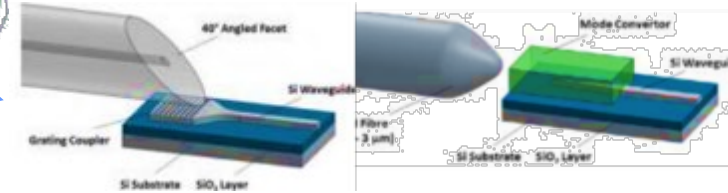


Laser integration

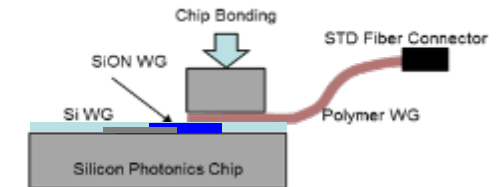


Multi-channel silicon photonics transceiver module

B PIC packaging platform (Fiber & polymer WG)

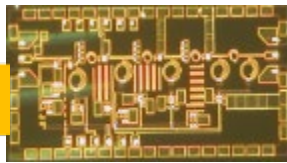
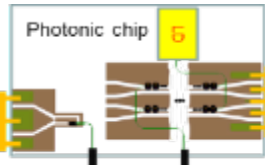
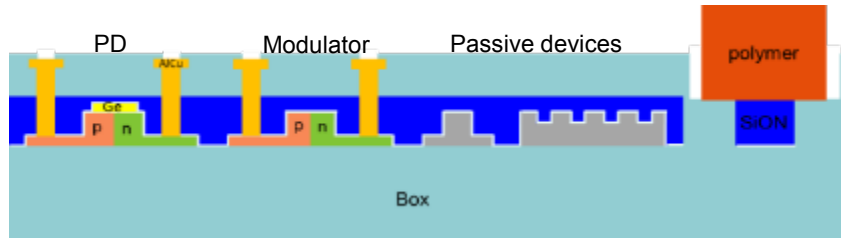


Low loss fiber coupling



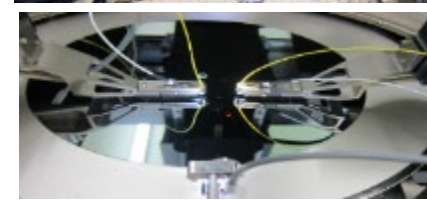
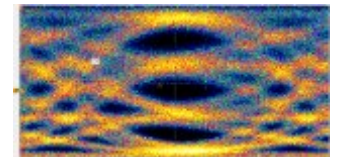
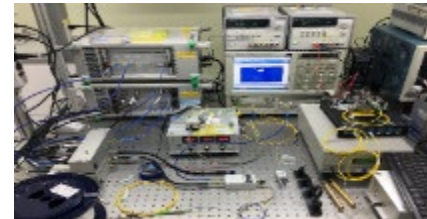
Multi-channel polymer WG array

A PIC integration



- Device design and integration
- EIC+PIC integration

C High speed testing platform



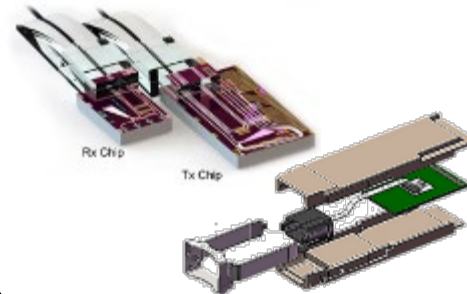
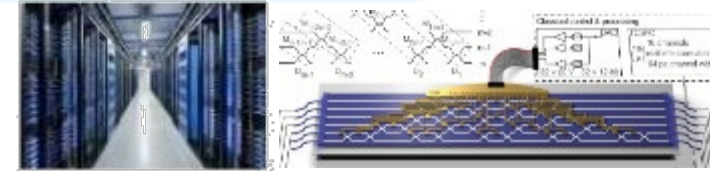
- Wafer level testing
- High freq. optical testing
- PAM4 analysis



Application of Photonic Integration

$\geq 1\text{Tb/s}$ optical transceiver

5G / quantum tech.



Reference: Browave, Mellanox

Co-Packaged Optics Switch



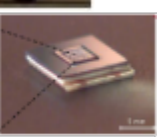
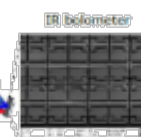
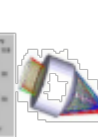
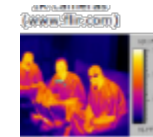
Reference: Luxtera

51.2Tb/s switch

HPC/CPU

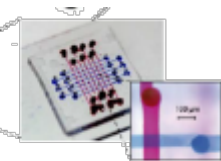
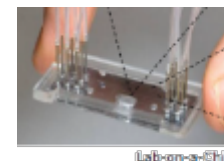


LiDAR
3D sensing
gyro



ex IR camera chip

Medical



ex bio-sensor chip

Silicon photonics
technology platform

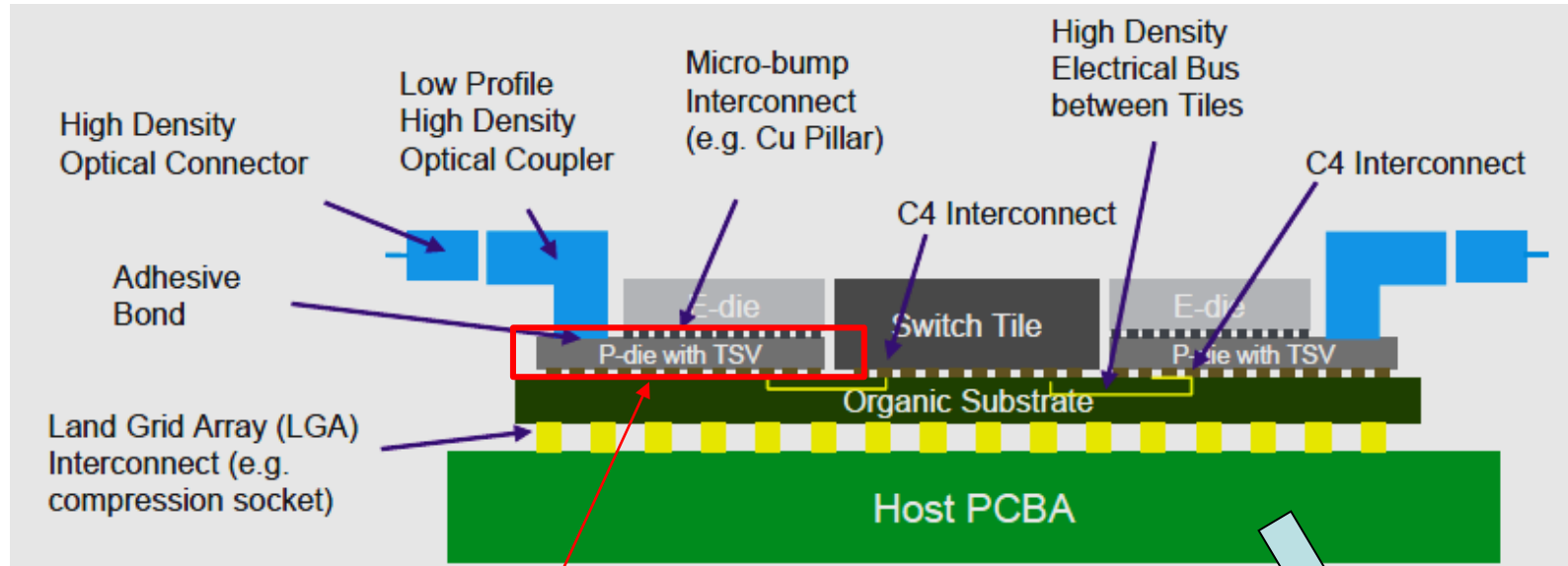


High Speed Opto-Electronic Testing Platform

- LIOS – Lab for integrated opto-electronics systems
- 100Gb/s PAM4 Tx/Rx device/module test
- Automatic passive device insertion loss test
 - Multiple channel allowed, ex 1x2, 1x4, 2x2, etc.
 - 8~20° fiber angle (not adjustable during test)
 - Full wafer map automatic measurement
 - O-band and C-band
- Automatic active device test
 - CP sorting purpose
 - Only for fixed wavelength, signal pattern and scope receiver condition
- Flexible manually test capability
 - On wafer, on chip, on board test
 - 2 RF, 2 fiber, 2 DC deployment



Luxtera Co-package for switch



PIC with TSV



- High density, high speed bus → TSV make sense



Conclusion

- People should do something to take the rapid growth of data traffic, one of them is silicon photonics
- ITRI build up a silicon photonics design, process, packaging and testing platform for the goal of 100Gb/s PAM4 data rate PIC/EIC integration
- Once silicon photonics works, it will drive many applications to be integrated by CMOS process, such as LiDAR
- ITRI would like to have deep collaboration with industry in silicon photonics related technologies and applications through the platform



Thank You